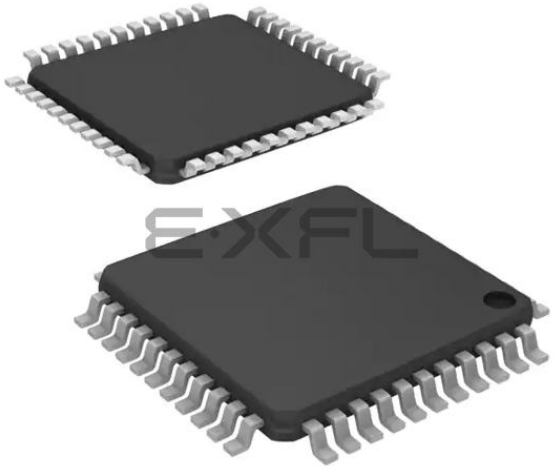

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	10MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f877-10e-pt

TABLE 1-2: PIC16F874 AND PIC16F877 PINOUT DESCRIPTION

Pin Name	DIP Pin#	PLCC Pin#	QFP Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	13	14	30	I	ST/CMOS(4)	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	14	15	31	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	1	2	18	I/P	ST	Master Clear (Reset) input or programming voltage input. This pin is an active low RESET to the device.
						PORTA is a bi-directional I/O port.
RA0/AN0	2	3	19	I/O	TTL	RA0 can also be analog input0.
RA1/AN1	3	4	20	I/O	TTL	RA1 can also be analog input1.
RA2/AN2/VREF-	4	5	21	I/O	TTL	RA2 can also be analog input2 or negative analog reference voltage.
RA3/AN3/VREF+	5	6	22	I/O	TTL	RA3 can also be analog input3 or positive analog reference voltage.
RA4/T0CKI	6	7	23	I/O	ST	RA4 can also be the clock input to the Timer0 timer/ counter. Output is open drain type.
RA5/$\overline{SS}$/AN4	7	8	24	I/O	TTL	RA5 can also be analog input4 or the slave select for the synchronous serial port.
						PORTB is a bi-directional I/O port. PORTB can be soft-ware programmed for internal weak pull-up on all inputs.
RB0/INT	33	36	8	I/O	TTL/ST(1)	RB0 can also be the external interrupt pin.
RB1	34	37	9	I/O	TTL	
RB2	35	38	10	I/O	TTL	
RB3/PGM	36	39	11	I/O	TTL	RB3 can also be the low voltage programming input.
RB4	37	41	14	I/O	TTL	Interrupt-on-change pin.
RB5	38	42	15	I/O	TTL	Interrupt-on-change pin.
RB6/PGC	39	43	16	I/O	TTL/ST(2)	Interrupt-on-change pin or In-Circuit Debugger pin. Serial programming clock.
RB7/PGD	40	44	17	I/O	TTL/ST(2)	Interrupt-on-change pin or In-Circuit Debugger pin. Serial programming data.

Legend: I = input O = output I/O = input/output P = power
— = Not used TTL = TTL input ST = Schmitt Trigger input

Note 1: This buffer is a Schmitt Trigger input when configured as an external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: This buffer is a Schmitt Trigger input when configured as general purpose I/O and a TTL input when used in the Parallel Slave Port mode (for interfacing to a microprocessor bus).
4: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

6.0 TIMER1 MODULE

The Timer1 module is a 16-bit timer/counter consisting of two 8-bit registers (TMR1H and TMR1L), which are readable and writable. The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow, which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

Timer1 can operate in one of two modes:

- As a timer
- As a counter

The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In Timer mode, Timer1 increments every instruction cycle. In Counter mode, it increments on every rising edge of the external clock input.

Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Timer1 also has an internal “RESET input”. This RESET can be generated by either of the two CCP modules (Section 8.0). Register 6-1 shows the Timer1 control register.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RC1/T1OSI/CCP2 and RC0/T1OSO/T1CKI pins become inputs. That is, the TRISC<1:0> value is ignored, and these pins read as ‘0’.

Additional information on timer modules is available in the PIC® MCU Mid-Range Family Reference Manual (DS33023).

REGISTER 6-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3 **T1OSCEN**: Timer1 Oscillator Enable Control bit
1 = Oscillator is enabled
0 = Oscillator is shut-off (the oscillator inverter is turned off to eliminate power drain)

bit 2 **$\overline{\text{T1SYNC}}$**: Timer1 External Clock Input Synchronization Control bit
When TMR1CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR1CS = 0:
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1 **TMR1CS**: Timer1 Clock Source Select bit
1 = External clock from pin RC0/T1OSO/T1CKI (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR1ON**: Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

8.0 CAPTURE/COMPARE/PWM MODULES

Each Capture/Compare/PWM (CCP) module contains a 16-bit register which can operate as a:

- 16-bit Capture register
- 16-bit Compare register
- PWM Master/Slave Duty Cycle register

Both the CCP1 and CCP2 modules are identical in operation, with the exception being the operation of the special event trigger. Table 8-1 and Table 8-2 show the resources and interactions of the CCP module(s). In the following sections, the operation of a CCP module is described with respect to CCP1. CCP2 operates the same as CCP1, except where noted.

CCP1 Module:

Capture/Compare/PWM Register1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. The special event trigger is generated by a compare match and will reset Timer1.

CCP2 Module:

Capture/Compare/PWM Register2 (CCPR2) is comprised of two 8-bit registers: CCPR2L (low byte) and CCPR2H (high byte). The CCP2CON register controls the operation of CCP2. The special event trigger is generated by a compare match and will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Additional information on CCP modules is available in the PIC® MCU Mid-Range Family Reference Manual (DS33023) and in application note AN594, “Using the CCP Modules” (DS00594).

TABLE 8-1: CCP MODE - TIMER RESOURCES REQUIRED

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

TABLE 8-2: INTERACTION OF TWO CCP MODULES

CCPx Mode	CCPy Mode	Interaction
Capture	Capture	Same TMR1 time-base
Capture	Compare	The compare should be configured for the special event trigger, which clears TMR1
Compare	Compare	The compare(s) should be configured for the special event trigger, which clears TMR1
PWM	PWM	The PWMs will have the same frequency and update rate (TMR2 interrupt)
PWM	Capture	None
PWM	Compare	None

8.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RC2/CCP1. An event is defined as one of the following:

- Every falling edge
- Every rising edge
- Every 4th rising edge
- Every 16th rising edge

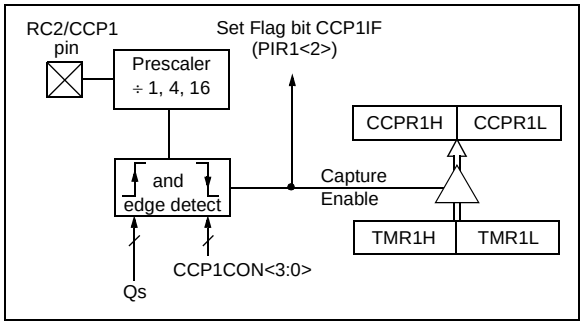
The type of event is configured by control bits CCP1M3:CCP1M0 (CCPxCON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. The interrupt flag must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value is overwritten by the new value.

8.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1 pin is configured as an output, a write to the port can cause a capture condition.

FIGURE 8-1: CAPTURE MODE OPERATION BLOCK DIAGRAM



8.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode, or Synchronized Counter mode, for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

8.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF, following any such change in operating mode.

8.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. Any RESET will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore, the first capture may be from a non-zero prescaler. Example 8-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 8-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF    CCP1CON      ; Turn CCP module off
MOVLW   NEW_CAPT_PS  ; Load the W reg with
                     ; the new prescaler
                     ; move value and CCP ON
MOVWF   CCP1CON      ; Load CCP1CON with this
                     ; value
```

9.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

The Master Synchronous Serial Port (MSSP) module is a serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I^2C)

Figure 9-1 shows a block diagram for the SPI mode, while Figure 9-5 and Figure 9-9 show the block diagrams for the two different I^2C modes of operation.

The Application Note AN734, “Using the PIC® MCU SSP for Slave I^2C™ Communication” describes the slave operation of the MSSP module on the PIC16F87X devices. AN735, “Using the PIC® MCU MSSP Module for I^2C™ Communications” describes the master operation of the MSSP module on the PIC16F87X devices.

10.1 USART Baud Rate Generator (BRG)

The BRG supports both the Asynchronous and Synchronous modes of the USART. It is a dedicated 8-bit baud rate generator. The SPBRG register controls the period of a free running 8-bit timer. In Asynchronous mode, bit BRGH (TXSTA<2>) also controls the baud rate. In Synchronous mode, bit BRGH is ignored. Table 10-1 shows the formula for computation of the baud rate for different USART modes which only apply in Master mode (internal clock).

Given the desired baud rate and FOSC, the nearest integer value for the SPBRG register can be calculated using the formula in Table 10-1. From this, the error in baud rate can be determined.

It may be advantageous to use the high baud rate (BRGH = 1), even for slower baud clocks. This is because the FOSC/(16(X + 1)) equation can reduce the baud rate error in some cases.

Writing a new value to the SPBRG register causes the BRG timer to be reset (or cleared). This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

10.1.1 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin.

TABLE 10-1: BAUD RATE FORMULA

SYNC	BRGH = 0 (Low Speed)	BRGH = 1 (High Speed)
0	(Asynchronous) Baud Rate = FOSC/(64(X+1))	Baud Rate = FOSC/(16(X+1))
1	(Synchronous) Baud Rate = FOSC/(4(X+1))	N/A

X = value in SPBRG (0 to 255)

TABLE 10-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented, read as '0'. Shaded cells are not used by the BRG.

10.4.2 USART SYNCHRONOUS SLAVE RECEPTION

The operation of the Synchronous Master and Slave modes is identical, except in the case of the SLEEP mode. Bit SREN is a “don't care” in Slave mode.

If receive is enabled by setting bit CREN prior to the SLEEP instruction, then a word may be received during SLEEP. On completely receiving the word, the RSR register will transfer the data to the RCREG register and if enable bit RCIE bit is set, the interrupt generated will wake the chip from SLEEP. If the global interrupt is enabled, the program will branch to the interrupt vector (0004h).

When setting up a Synchronous Slave Reception, follow these steps:

1. Enable the synchronous master serial port by setting bits SYNC and SPEN and clearing bit CSRC.
2. If interrupts are desired, set enable bit RCIE.
3. If 9-bit reception is desired, set bit RX9.
4. To enable reception, set enable bit CREN.
5. Flag bit RCIF will be set when reception is complete and an interrupt will be generated, if enable bit RCIE was set.
6. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
7. Read the 8-bit received data by reading the RCREG register.
8. If any error occurred, clear the error by clearing bit CREN.
9. If using interrupts, ensure that GIE and PEIE (bits 7 and 6) of the INTCON register are set.

TABLE 10-11: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh, 8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	R0IF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
1Ah	RCREG	USART Receive Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented, read as '0'. Shaded cells are not used for synchronous slave reception.

Note 1: Bits PSPIE and PSPIF are reserved on PIC16F873/876 devices, always maintain these bits clear.

REGISTER 11-2: ADCON1 REGISTER (ADDRESS 9Fh)

U-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	—	—	—	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

bit 7 **ADFM:** A/D Result Format Select bit
1 = Right justified. 6 Most Significant bits of ADRESH are read as ‘0’.
0 = Left justified. 6 Least Significant bits of ADRESL are read as ‘0’.

bit 6-4 **Unimplemented:** Read as '0'

bit 3-0 **PCFG3:PCFG0**: A/D Port Configuration Control bits:

PCFG3: PCFG0	AN7(1) RE2	AN6(1) RE1	AN5(1) RE0	AN4 RA5	AN3 RA3	AN2 RA2	AN1 RA1	AN0 RA0	VREF+	VREF-	CHAN/ Refs(2)
0000	A	A	A	A	A	A	A	A	VDD	VSS	8/0
0001	A	A	A	A	VREF+	A	A	A	RA3	VSS	7/1
0010	D	D	D	A	A	A	A	A	VDD	VSS	5/0
0011	D	D	D	A	VREF+	A	A	A	RA3	VSS	4/1
0100	D	D	D	D	A	D	A	A	VDD	VSS	3/0
0101	D	D	D	D	VREF+	D	A	A	RA3	VSS	2/1
011x	D	D	D	D	D	D	D	D	VDD	VSS	0/0
1000	A	A	A	A	VREF+	VREF-	A	A	RA3	RA2	6/2
1001	D	D	A	A	A	A	A	A	VDD	VSS	6/0
1010	D	D	A	A	VREF+	A	A	A	RA3	VSS	5/1
1011	D	D	A	A	VREF+	VREF-	A	A	RA3	RA2	4/2
1100	D	D	D	A	VREF+	VREF-	A	A	RA3	RA2	3/2
1101	D	D	D	D	VREF+	VREF-	A	A	RA3	RA2	2/2
1110	D	D	D	D	D	D	D	A	VDD	VSS	1/0
1111	D	D	D	D	VREF+	VREF-	D	A	RA3	RA2	1/2

A = Analog input D = Digital I/O

Note 1: These channels are not available on PIC16F873/876 devices.
2: This column indicates the number of analog channels available as A/D inputs and the number of analog channels used as voltage reference inputs.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

The ADRESH:ADRESL registers contain the 10-bit result of the A/D conversion. When the A/D conversion is complete, the result is loaded into this A/D result register pair, the GO/DONE bit (ADCON0<2>) is cleared and the A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 11-1.

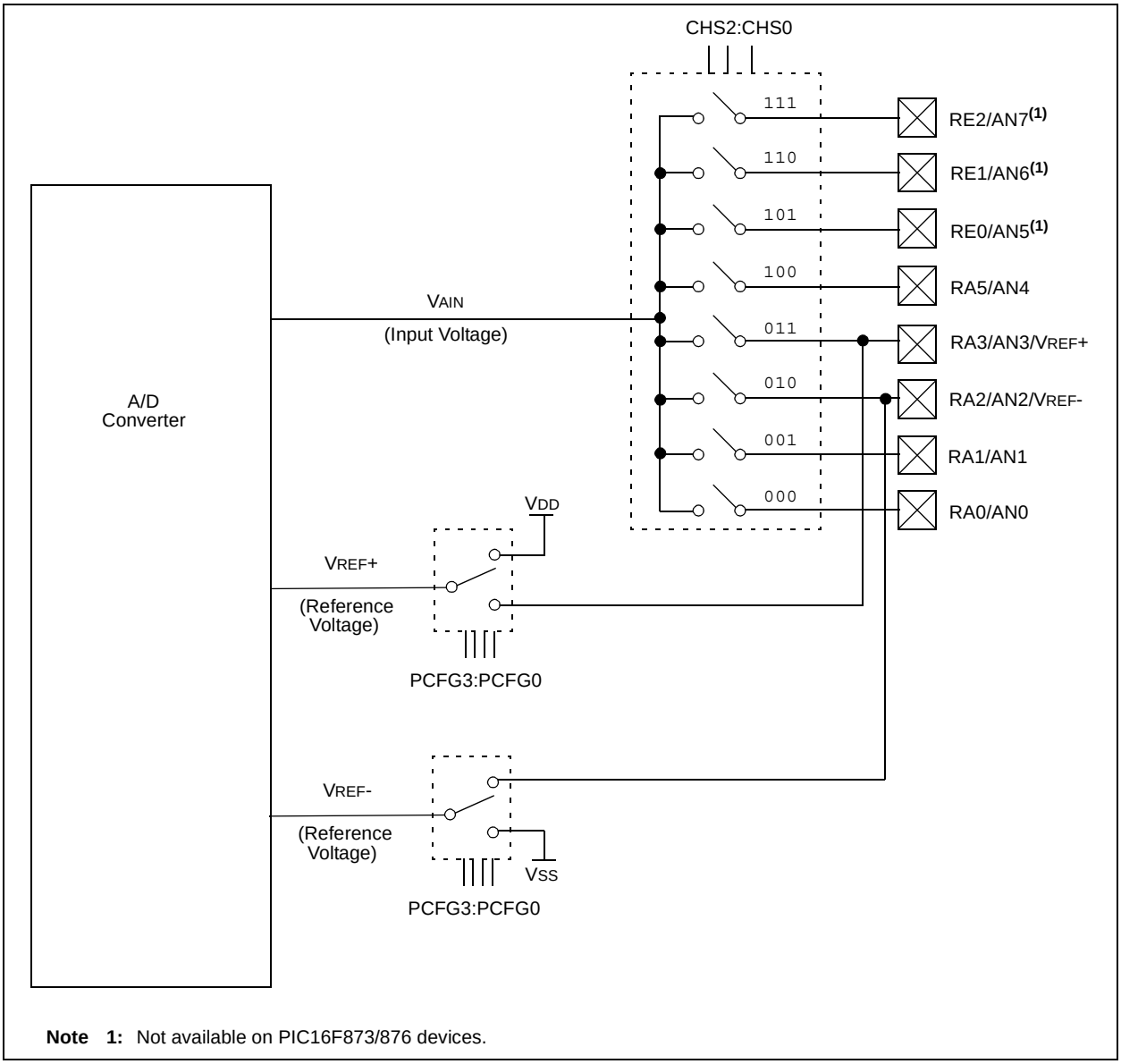
After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as inputs.

To determine sample time, see Section 11.1. After this acquisition time has elapsed, the A/D conversion can be started.

These steps should be followed for doing an A/D Conversion:

1. Configure the A/D module:
   - Configure analog pins/voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D conversion clock (ADCON0)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set PEIE bit
   - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared (with interrupts enabled); OR
   - Waiting for the A/D interrupt
6. Read A/D result register pair (ADRESH:ADRESL), clear bit ADIF if required.
7. For the next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before the next acquisition starts.

FIGURE 11-1: A/D BLOCK DIAGRAM



Note 1: Not available on PIC16F873/876 devices.

11.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires a minimum 12TAD per 10-bit conversion. The source of the A/D conversion clock is software selected. The four possible options for TAD are:

- 2TOSC
- 8TOSC
- 32TOSC
- Internal A/D module RC oscillator (2-6 μs)

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 μs.

Table 11-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 11-1: TAD vs. MAXIMUM DEVICE OPERATING FREQUENCIES (STANDARD DEVICES (C))

AD Clock Source (TAD)		Maximum Device Frequency
Operation	**ADCS1:ADCS0**	**Max.**
2TOSC	00	1.25 MHz
8TOSC	01	5 MHz
32TOSC	10	20 MHz
RC(1, 2, 3)	11	**(Note 1)**

Note 1: The RC source has a typical TAD time of 4 μs, but can vary between 2-6 μs.
2: When the device frequencies are greater than 1 MHz, the RC A/D conversion clock source is only recommended for SLEEP operation.
3: For extended voltage devices (LC), please refer to the Electrical Characteristics (Sections 15.1 and 15.2).

11.3 Configuring Analog Port Pins

The ADCON1 and TRIS registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, any pin configured as an analog input channel will read as cleared (a low level). Pins configured as digital inputs will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

2: Analog levels on any pin that is defined as a digital input (including the AN7:AN0 pins), may cause the input buffer to consume current that is out of the device specifications.

TABLE 12-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Crystal Freq.	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
These values are for design guidance only. See notes following this table.			
Crystals Used			
32 kHz	Epson C-001R32.768K-A	± 20 PPM	
200 kHz	STD XTL 200.000KHz	± 20 PPM	
1 MHz	ECS ECS-10-13-1	± 50 PPM	
4 MHz	ECS ECS-40-20-1	± 50 PPM	
8 MHz	EPSON CA-301 8.000M-C	± 30 PPM	
20 MHz	EPSON CA-301 20.000M-C	± 30 PPM	

Note 1: Higher capacitance increases the stability of oscillator, but also increases the start-up time.

2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

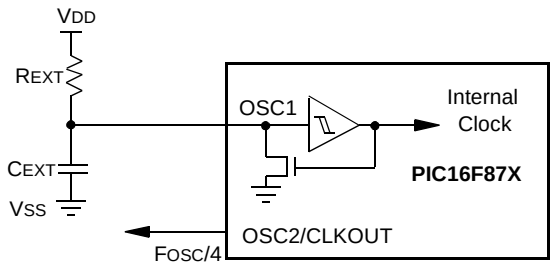
3: R_S may be required in HS mode, as well as XT mode, to avoid overdriving crystals with low drive level specification.

4: When migrating from other PIC® MCU devices, oscillator performance should be verified.

12.2.3 RC OSCILLATOR

For timing insensitive applications, the “RC” device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 12-3 shows how the R/C combination is connected to the PIC16F87X.

FIGURE 12-3: RC OSCILLATOR MODE



14.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can also link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian is a librarian for pre-compiled code to be used with the MPLINK object linker. When a routine from a library is called from another source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. The MPLIB object librarian manages the creation and modification of library files.

The MPLINK object linker features include:

- Integration with MPASM assembler and MPLAB C17 and MPLAB C18 C compilers.
- Allows all memory areas to be defined as sections to provide link-time flexibility.

The MPLIB object librarian features include:

- Easier linking because single libraries can be included instead of many smaller files.
- Helps keep code maintainable by grouping related modules together.
- Allows libraries to be created and modules to be added, listed, replaced, deleted or extracted.

14.5 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC-hosted environment by simulating the PIC MCU series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user-defined key press, to any of the pins. The execution can be performed in single step, execute until break, or trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and the MPLAB C18 C compilers and the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent multi-project software development tool.

14.6 MPLAB ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB ICE universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC MCU microcontrollers (MCUs). Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE in-circuit emulator system has been designed as a real-time emulation system, with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows environment were chosen to best make these features available to you, the end user.

14.7 ICEPIC In-Circuit Emulator

The ICEPIC low cost, in-circuit emulator is a solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X and PIC16CXXX families of 8-bit One-Time-Programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules, or daughter boards. The emulator is capable of emulating without target application circuitry being present.

15.1 DC Characteristics: PIC16F873/874/876/877-04 (Commercial, Industrial) PIC16F873/874/876/877-20 (Commercial, Industrial) PIC16LF873/874/876/877-04 (Commercial, Industrial) (Continued)

PIC16LF873/874/876/877-04 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial				
PIC16F873/874/876/877-04 PIC16F873/874/876/877-20 (Commercial, Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial 0°C ≤ TA ≤ +70°C for commercial				
Param No.	**Symbol**	**Characteristic/ Device**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IPD	**Power-down Current(3,5)**					
D020		16LF87X	—	7.5	30	µA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D020		16F87X	—	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021		16LF87X	—	0.9	5	µA	VDD = 3.0V, WDT enabled, 0°C to +70°C
D021		16F87X	—	1.5	16	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021A		16LF87X		0.9	5	µA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021A		16F87X		1.5	19	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D023	ΔIBOR	**Brown-out Reset Current(6)**	—	85	200	µA	BOR enabled, VDD = 5.0V

Legend: Rows with standard voltage device data only are shaded for improved readability.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading, switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

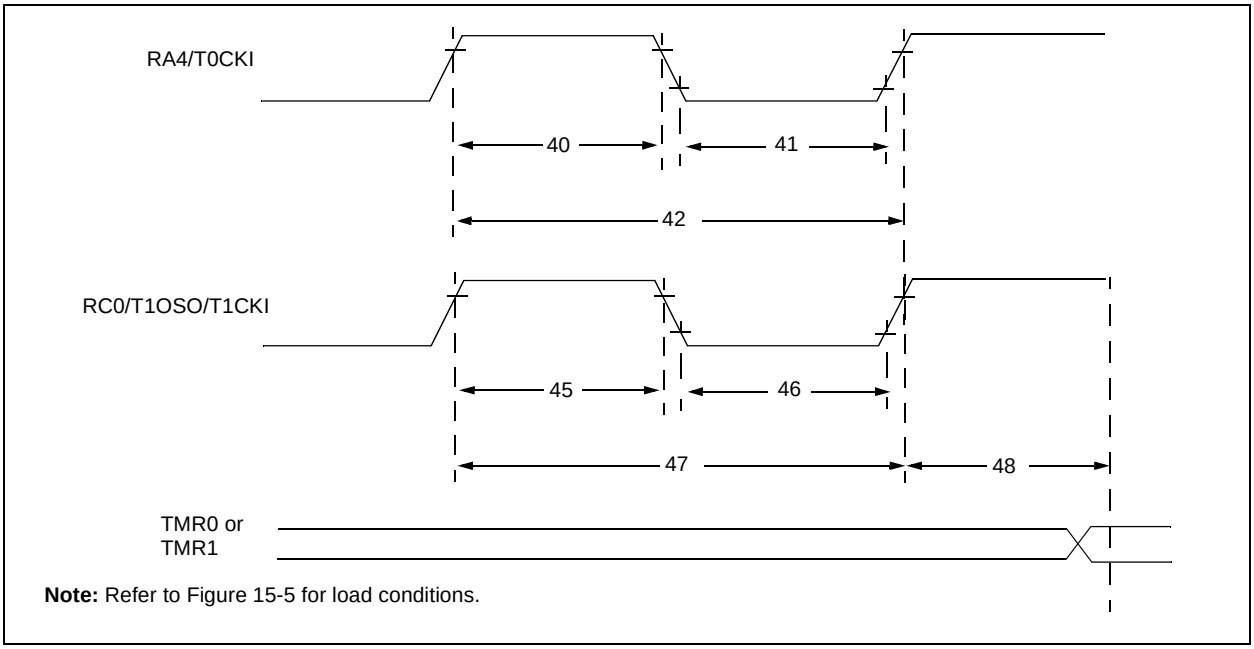
4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: When BOR is enabled, the device will operate correctly until the VBOR voltage trip point is reached.

FIGURE 15-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 15-5 for load conditions.

TABLE 15-4: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Symbol	Characteristic			Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width		No Prescaler	0.5TCY + 20	—	—	ns	Must also meet parameter 42
				With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period		No Prescaler	TCY + 40	—	—	ns	
				With Prescaler	Greater of: 20 or TCY + 40 / N	—	—	ns	N = prescale value (2, 4,..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	Standard(**F**)	15	—	—	ns	
				Extended(**LF**)	25	—	—	ns	
			Asynchronous	Standard(**F**)	30	—	—	ns	
				Extended(**LF**)	50	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, Prescaler = 1		0.5TCY + 20	—	—	ns	Must also meet parameter 47
			Synchronous, Prescaler = 2,4,8	Standard(**F**)	15	—	—	ns	
				Extended(**LF**)	25	—	—	ns	
			Asynchronous	Standard(**F**)	30	—	—	ns	
				Extended(**LF**)	50	—	—	ns	
47*	Tt1P	T1CKI input period	Synchronous	Standard(**F**)	Greater of: 30 OR TCY + 40 / N	—	—	ns	N = prescale value (1, 2, 4, 8)
				Extended(**LF**)	Greater of: 50 OR TCY + 40 / N				N = prescale value (1, 2, 4, 8)
			Asynchronous	Standard(**F**)	60	—	—	ns	
				Extended(**LF**)	100	—	—	ns	
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)			DC	—	200	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment			2TOSC	—	7TOSC	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

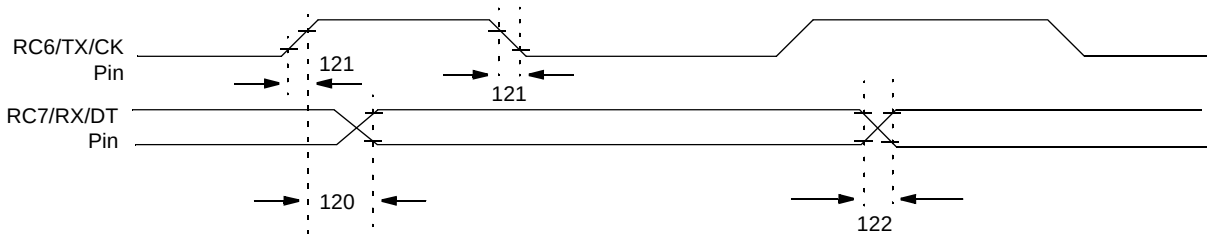
TABLE 15-9: I^2C BUS DATA REQUIREMENTS

Param No.	Sym	Characteristic		Min	Max	Units	Conditions
100	Thigh	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	0.5TCY	—		
101	Tlow	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	0.5TCY	—		
102	Tr	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
103	Tf	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10 to 400 pF
90	Tsu:sta	START condition setup time	100 kHz mode	4.7	—	μs	Only relevant for Repeated START condition
			400 kHz mode	0.6	—	μs	
91	Thd:sta	START condition hold time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106	Thd:dat	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	Tsu:dat	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92	Tsu:sto	STOP condition setup time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109	Taa	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110	Tbuf	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast mode (400 kHz) I^2C bus device can be used in a standard mode (100 kHz) I^2C bus system, but the requirement that Tsu:dat ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+ Tsu:dat = 1000 + 250 = 1250 ns (according to the standard mode I^2C bus specification) before the SCL line is released.

FIGURE 15-19: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



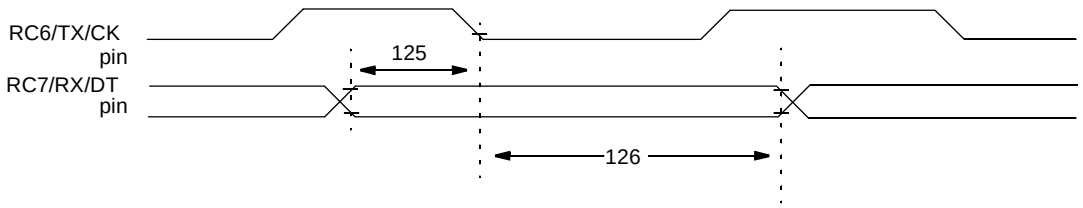
Note: Refer to Figure 15-5 for load conditions.

TABLE 15-10: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	Standard(**F**)	—	—	80	ns	
			Extended(**LF**)	—	—	100	ns	
121	Tckrf	Clock out rise time and fall time (Master mode)	Standard(**F**)	—	—	45	ns	
			Extended(**LF**)	—	—	50	ns	
122	Tdtrf	Data out rise time and fall time	Standard(**F**)	—	—	45	ns	
			Extended(**LF**)	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-20: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 15-5 for load conditions.

TABLE 15-11: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK ↓ (DT setup time)	15	—	—	ns	
126	TckL2dtl	Data hold after CK ↓ (DT hold time)	15	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 16-3: TYPICAL IDD vs. FOSC OVER VDD (XT MODE)

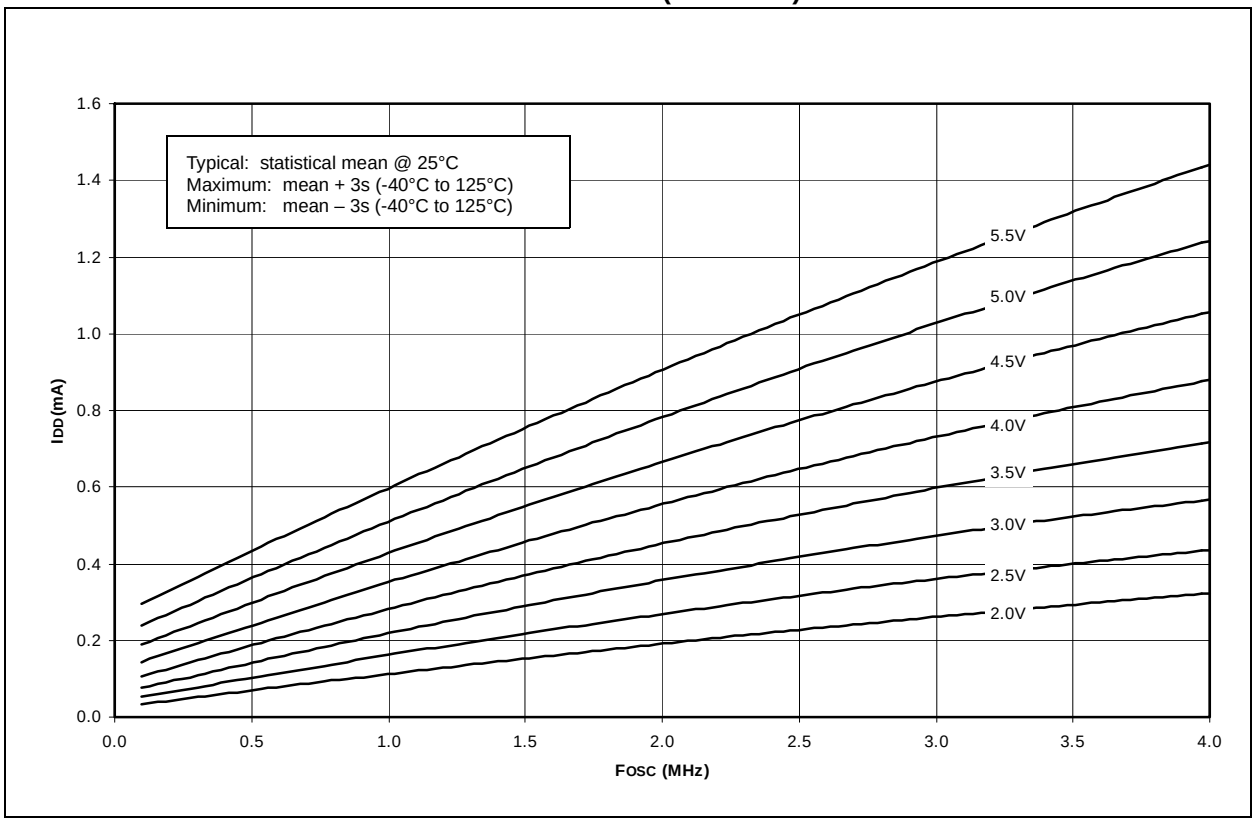


FIGURE 16-4: MAXIMUM IDD vs. FOSC OVER VDD (LP MODE)

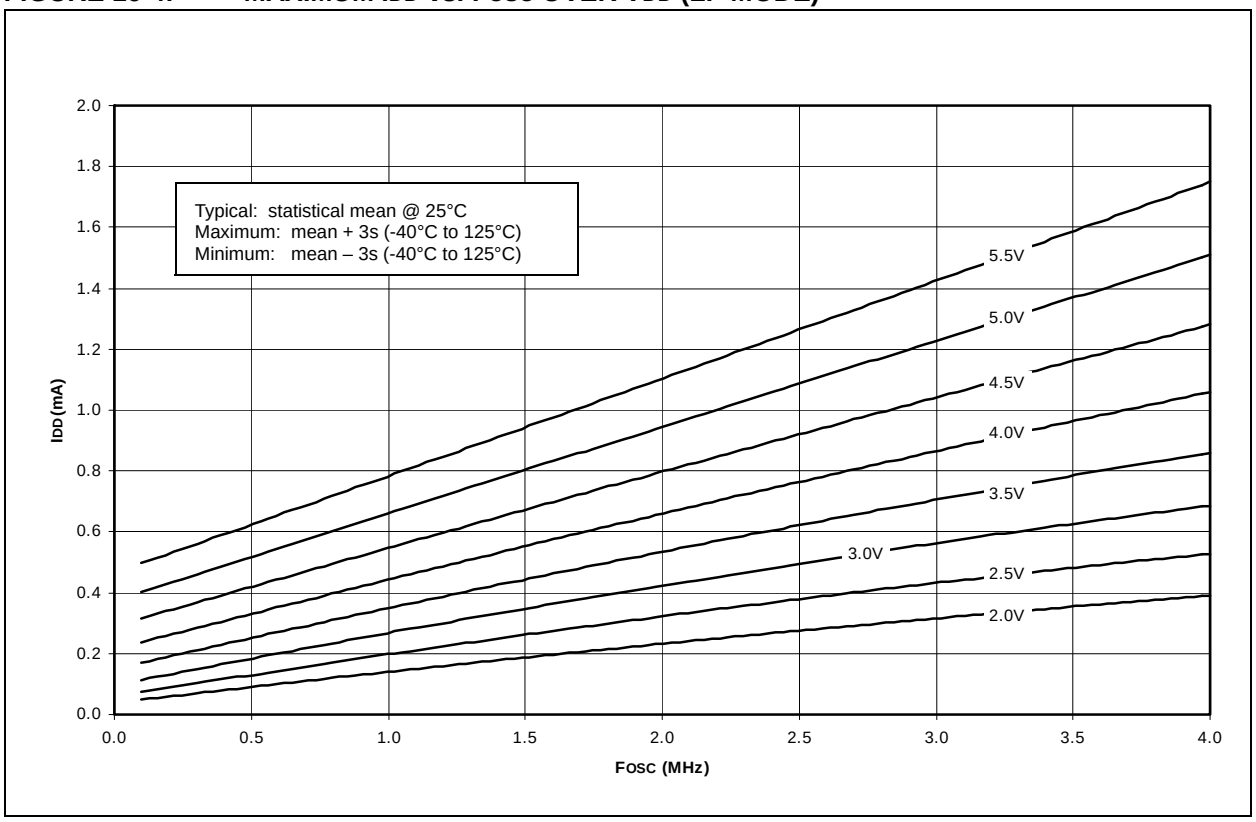


FIGURE 16-5: TYPICAL IDD vs. FOSC OVER VDD (LP MODE)

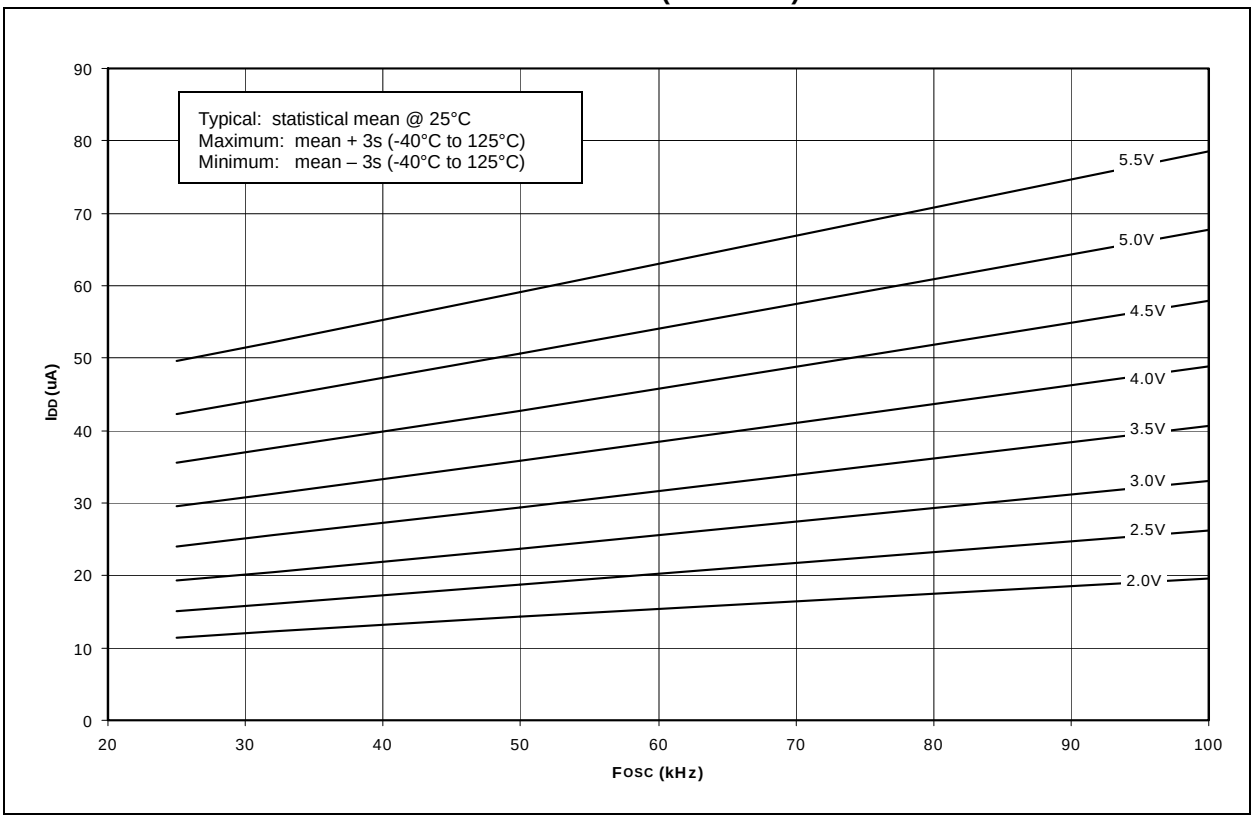
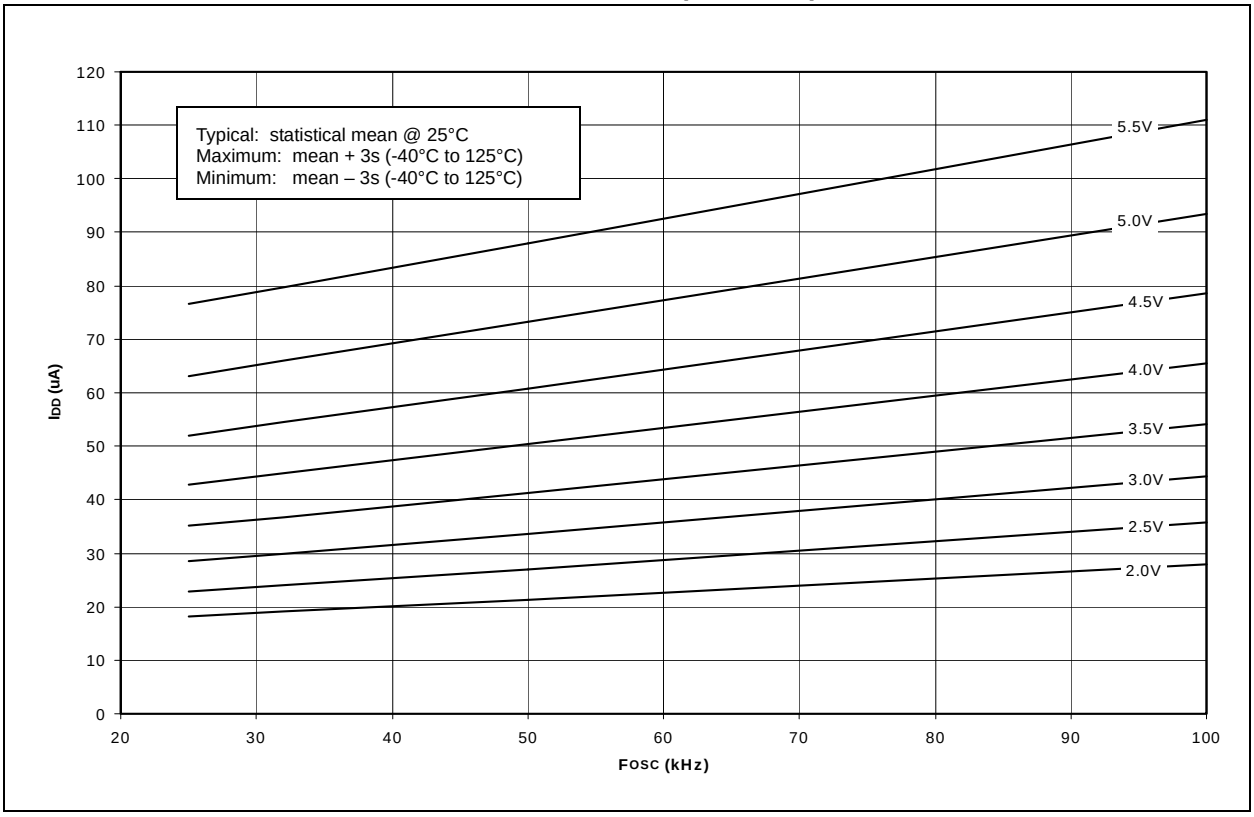


FIGURE 16-6: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)



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